



SLOVENSKI STANDARD
oSIST prEN IEC 60749-24:2025
01-februar-2025

**Polprevodniški elementi - Metode za mehansko in klimatsko preskušanje - 24. del:
Povečana odpornost na vlago**

Semiconductor devices - Mechanical and climatic test methods - Part 24: Accelerated moisture resistance - Unbiased hast

Halbleiterbauelemente – Mechanische und klimatische Prüfverfahren - Teil 24:
Beschleunigte Feuchtigkeitsbeständigkeit – Unvoreingenommene Hast

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie
24: Résistance à l'humidité accélérée - Hast sans polarisation

Ta slovenski standard je istoveten z: prEN IEC 60749-24:2024

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ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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en



47/2863/CDV

COMMITTEE DRAFT FOR VOTE (CDV)

PROJECT NUMBER:

IEC 60749-24 ED2

DATE OF CIRCULATION:

2024-09-06

CLOSING DATE FOR VOTING:

2024-11-29

SUPERSEDES DOCUMENTS:

47/2858/RR

IEC TC 47 : SEMICONDUCTOR DEVICES	
SECRETARIAT: Korea, Republic of	SECRETARY: Mr Cheolung Cha
OF INTEREST TO THE FOLLOWING COMMITTEES: TC 91, TC 104	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED: Environment, Safety	
<input type="checkbox"/> SUBMITTED FOR CENELEC PARALLEL VOTING	<input checked="" type="checkbox"/> NOT SUBMITTED FOR CENELEC PARALLEL VOTING

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TITLE:

Semiconductor devices - Mechanical and climatic test methods - Part 24: Accelerated moisture resistance - Unbiased HAST

PROPOSED STABILITY DATE: 2030

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 24: Accelerated moisture resistance – Unbiased HAST**

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IEC 60749-5 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

This second edition, based on JEDEC document JESD22-A118B.01, cancels and replaces the first edition published in 2004. It is used with permission of the copyright holder, JEDEC Solid State Technology Association. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) rearrangement of clauses to reposition requirements;
- b) addition of 2 notes to the post-test electrical procedures.

54 The text of this International Standard is based on the following documents:

Draft	Report on voting
47/XX/FDIS	47/XX/RVD

55
56 Full information on the voting for its approval can be found in the report on voting indicated in
57 the above table.

58 The language used for the development of this International Standard is English.

59 This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in
60 accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement,
61 available at www.iec.ch/members_experts/refdocs. The main document types developed by
62 IEC are described in greater detail at www.iec.ch/publications.

63 A list of all parts of the IEC 60749 series, under the general title *Semiconductor devices –*
64 *Mechanical and climatic test methods*, can be found in the IEC website.

65 The committee has decided that the contents of this document will remain unchanged until the
66 stability date indicated on the IEC website under webstore.iec.ch in the data related to the
67 specific document. At this date, the document will be

- 68 • reconfirmed,
- 69 • withdrawn,
- 70 • replaced by a revised edition, or
- 71 • amended.

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